Amendment to the Claims

Please amend claim 11 and 23 as follows:

11. (currently amended) A process for the partial demetallization of a ~~first~~ multilayer laminate ~~substrate comprising a coextruded film~~ comprising a first film and a second film wherein the first film comprises a first polymeric layer and a metallic layer and the second film comprises a second polymeric layer and an adhesive layer ~~a polypropylene layer, an adhesive layer and a metallic layer~~, the process comprising applying an etchant lacquer to the metallic layer of the first polymeric film, applying an adhesive layer to the second polymeric film, and joining the first film and the second film wherein the adhesive layer of the second film contacts the partially demetallized layer of the first film, wherein the lamination step is in-line with the demetallization step, wherein the etchant lacquer comprises ~~comprising~~ at least one metal dissolving etchant on the metallic layer in a quantity of about the ~~stoechiometrical~~ stoichiometrical amount needed to dissolve the metallic layer and to eliminate any chemical reactivity of the at least one etchant towards the adhesive layer, wherein the dissolved metal remains within the multilayer laminate ~~substrate~~, and the dissolution of the metal creates a substantially transparent window in the metallic layer in a washing-free step.

12. (Previously Presented) The process of claim 11, wherein the process is carried out on standard gravure or flexo printing presses or coating equipment.

13. (cancelled)

14. (Currently Amended) The process of claim 11, further comprising a coating operation for treating the first ~~multilayer substrate~~ film.

15. (Currently Amended) The process of claim 11, further comprising a printing operation for treating the first ~~multilayer substrate~~ film.

16. (Currently Amended) The process of claim 11, further comprising a coating operation and a printing operation for treating the first ~~multilayer substrate~~ film.

17. (Currently Amended) The process of claim 14, wherein the coating operation comprising a coating in register with the demetallized area on a surface of the ~~substrate~~ first polymeric layer that is different than where the demetallization is carried out.

18. (Currently Amended) The process of claim 15, wherein the printing operation comprises a patterned print in register with the demetallized area on a surface of the ~~substrate~~ first polymeric layer that is different than where the demetallization is carried out.

19. (Previously Presented) The process of claim 12, wherein the amount the etchant lacquer is fine-tuned by choosing a suitable gravure cylinder depth.

20. (Previously Presented) The process of claim 11, wherein the amount the etchant lacquer is fine-tuned by adapting the concentration of the at least one etchant.

21. (Previously Presented) The process of claim 12, wherein the amount of the etchant lacquer is fine-tuned by choosing a suitable gravure cylinder depth and by adapting the concentration of the at least one etchant.

22. (Previously Presented) The process of claim 11, wherein the demetallization step achieves a light transmission of at least 90% within the demetallized area.

23. (Currently Amended) The process of claim 11, wherein the concentration of the at least one etchant corresponds to a slight excess of the ~~stoechiometrical~~ stoichiometrical amount needed to dissolve the amount of metal present on the multilayer ~~substrate~~ laminate.

24. (Currently Amended) A multilayer ~~substrate~~ laminate obtainable by the process of claim 11, comprising a window in a supported metallic layer wherein the window has the total quantity of a residue resulting from the demetallization by means of the etchant lacquer.

25. (New) The process of claim 11 wherein the first polymeric layer is biaxially oriented polypropylene.

26. (New) The process of claim 11 wherein the second polymeric layer is biaxially oriented polypropylene.

27. (New) The process according to claim 11 wherein the first polymeric layer is biaxially oriented polypropylene and the second polymeric layer is biaxially oriented polypropylene.

28. (New) The process according to claim 11 wherein the metallic layer is aluminum.

29 (New) The process according to claim 27 wherein the metallic layer is aluminum.